'Applicant: Haruo Hyodo et al.

Serial No.: 09/963,267

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: September 26, 2001

Page: 2 of 3

In the specification:

Please amend the title as follows:

A Hollow Airtight Semiconductor Device Package and Manufacturing Method thereof

Attorney's Docket No.: 10417-101001 / F51-

136645M/TOM